

DERWENT- 2002-506200

ACC-NO:

DERWENT- 200254

WEEK:

COPYRIGHT 2007 DERWENT INFORMATION LTD

TITLE: Method to accurately define the decapsulated area of plastic package - by dropping the etching liquid in an automatic transportation manner to remove the sealed cap portion

INVENTOR: YE, M

PATENT-ASSIGNEE: TAIWAN SEMICONDUCTOR MFG CO LTD[TASEN]

PRIORITY-DATA: 2000TW-0102897 (February 19, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
TW 463340 A	November 11, 2001	N/A	000	H01L 023/28

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
TW 463340A	N/A	2000TW-0102897	February 19, 2000

INT-CL (IPC): H01L023/28

ABSTRACTED-PUB-NO: TW 463340A

BASIC-ABSTRACT:

NOVELTY - A method to accurately define the decapsulated area of plastic package is disclosed, wherein a mask with a size larger than that of the plastic package is pasted on the surface of the plastic package. Next, the decapsulated area is defined in this mask according to the size and position of the semiconductor chip of the plastic package. Then this plastic package is heated to a specific temperature, and the etching liquid is dropped on the decapsulated area of this plastic package manually, or the etching liquid with a specific temperature is dropped on the decapsulated area of this plastic package in an automatic transportation manner to remove the sealed cap portion of the decapsulated area and expose the semiconductor chip. Then the semiconductor chip is cleaned.

CHOSEN- Dwg.1/1
DRAWING:

TITLE-TERMS: METHOD ACCURACY DEFINE AREA PLASTIC PACKAGE DROP ETCH LIQUID AUTOMATIC
TRANSPORT MANNER REMOVE SEAL CAP PORTION

DERWENT-CLASS: L03 U11

CPI-CODES: L04-C07; L04-C20;

EPI-CODES: U11-E02A1;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2002-143832

Non-CPI Secondary Accession Numbers: N2002-400411

